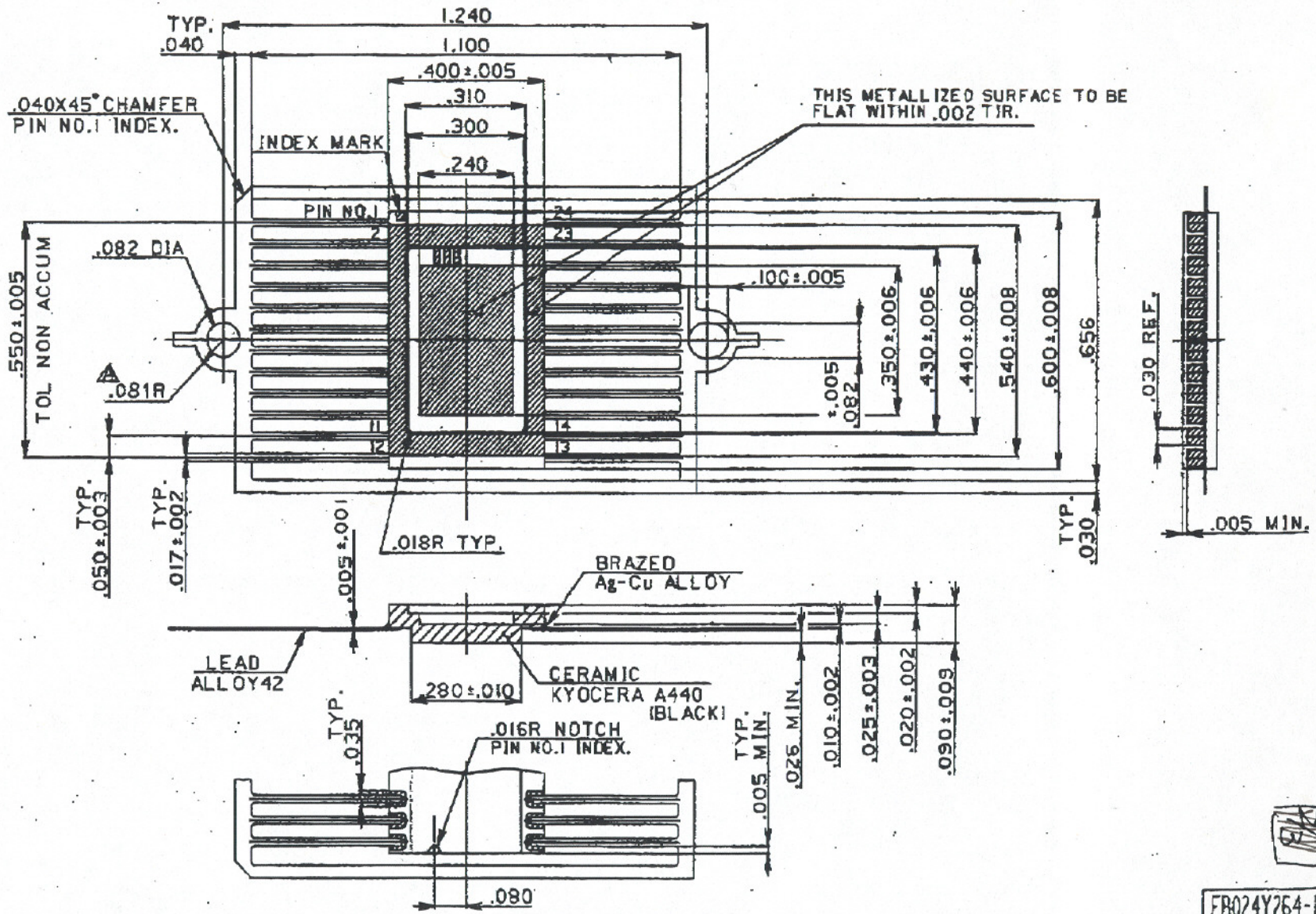
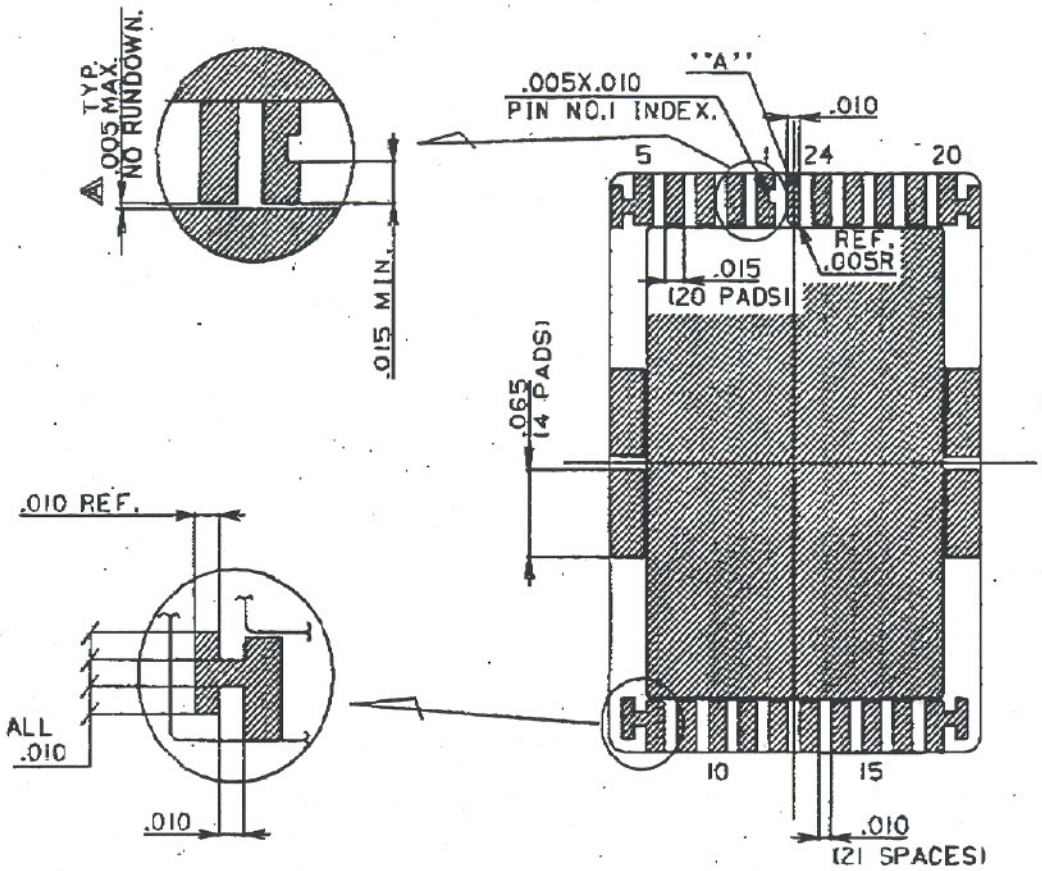
99年10月28日09時23分 発信:KAI/SDG ME CSO 着信:京セラ株半導体海外営業(2) SC海外5課



MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					24 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	M.S	S.T T.A	M.K	APR.17'90
					SCALE 4/1	MATERIAL AS INDICATED				
⚠	CHANGED: 073R → 081R	JUL'90	T.A		KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-F90264-A			SHEET 1/2
	CHANGED	DATE	DRAWN	CHECKED APPROVED						

FB024Y264-1 S=8 D=8

99年10月28日09時23分 発生:KAI/SDG ME CSO 発信:京セラ株式会社海外営業(2) SC海外5課



NOTES.

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. "A" PAD TO BE ELECTRICALLY CONNECTED TO DIE ATTACH AREA.
6. LEAD RESISTANCE : 0.30 MAX.

BONDING PATTERN

MODIFICATION		DATE	DRAWN	CHECKED	APPROVED
A	ADDED: .005MAXTYP NO RUN DOWN.	JUL 6'90			
	CHANGED				

NAME 24 LEAD FLAT PACKAGE
SCALE 10/1
MATERIAL —
TOLERANCE UNLESS OTHERWISE SPECIFIED ± —
THIRD ANGLE PROJECTION

DRAWN	CHECKED	APPROVED	DATE
M.S	S.T T.A	M.K	APR.17'90

KYOCERA CORPORATION
KYOTO JAPAN

DRAWING NO. KD-F90264-A
SHEET 2/2